INTRODUCES

MICRO ELECTRONICS
PROTO & PRODUCTION

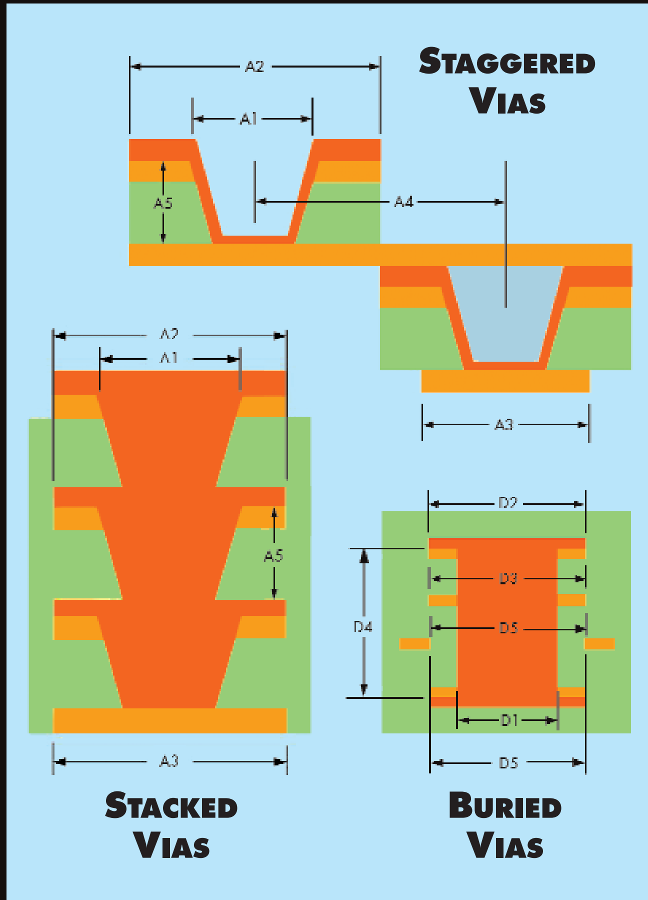
- SUB 2-MIL LINES
- .25 MM PITCH
- STACKED BLIND & BURIED VIAS
- ULTRA THIN MULTI LAYER BOARDS (12 LAYERS, 28-MIL THICKNESS)

Complete Design Assistance

www.micropcb.com

Micro Electronics

Micro Electronics Via Structures



For Complete Design Guideline Details, Visit:
www.micropcb.com

Micro Electronics Capabilities

Microvia from Outer Layer to 1st Inner Layer

A1	Blind/Buried via laser drill diameter	.002"
A2	Laser drill capture pad diameter	A1 + .004"
A3	Laser drill target pad diameter	A1 + .004"
A4	Distance center to center staggered vias	.005"
A5:A1	Laser via plating aspect ratio	>1:1

Filled (Copper) Mechanical Drill Buried Via

D1	Buried via mechanical drill diameter	.004"
D2	Mechanical drill capture pad diameter	D1 + .008"
D3	Mechanical drill target pad diameter	D1 + .008"
D4	Dielectric thickness	.005"
D5	Innerlayer antipad clearance diameter	D1 + .012"
D4:D1	Mechanical via plating aspect ratio	>16:1

LPI Soldermask

Minimum thickness	.0005"
Registration tolerance	+/-.001"
Minimum SMD pad spacing for mask between pads	.005"
Minimum web width	.002"

Legend Specifications

Minimum text line width	.0025"
Registration tolerance	+/-.003"
Minimum character height	.015"

Complete Design Assistance

- **Design Assistance to Optimize Costs**
- **Impedance Stack-up Assistance**
- **Design for Manufacturability (DFM) Assistance**

Military • Medical • Automotive

Please call us at:
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